- 1. A resin-coated copper foil, wherein the resin-coated copper foil has the resin layer on one surface of the copper foil, wherein the resin layer has a resin composition as follows:
 - (1) 20 to 70 parts by weight of an epoxy resin
- (2) 5 to 30 parts by weight of a high polymer having a crosslinkable functional group in its molecule and a crosslinking agent therefor in combination
 - (3) 10 to 60 parts by weight of a compound having a structure shown in

10 Formula 1:

Formula 1

 \mathbb{C}^{H}

15

5

, wherein n is an integer of one or more,

R:
$$-CH_2$$

Or

 $-CH_2$
 CH_2
 CH_2
 CH_2
 CH_3
 $CH_$

- 2. The resin-coated copper foil according to claim 1, wherein the high polymer having a crosslinkable functional group in its molecule and the crosslinking agent therefor are one or more selected from the group consisting of a polyvinyl acetal resin, a phenoxy resin, a polyethersulfone resin, a carboxyl modified acrylonitrile-butadiene resin and an aromatic polyamide resin polymer, which are all soluble in a solvent.
 - 3. A multilayer printed wiring board, comprising the resin-coated copper foil according to claim 1 or 2.